

In the Claims:

Please delete the word "Claims" and insert --What is claimed is:-- therefor.

Please amend the claims as follows:

1. (currently amended) ~~A photoconductor (102, 202) for conducting light, characterized in that to a surface of the photoconductor (102, 202), there is induced electroconductive material (110, 210);~~ An apparatus comprising:

a photoconductor having a surface,
an electroconductive material induced on said surface of the photoconductor, which material is connectable to a ground plane in order to conduct electrostatic discharges through the electroconductive material (110, 210) of the photoconductor (102, 202) to the ground plane.

2. (currently amended) ~~A photoconductor (102, 202)~~ The apparatus according to claim 1, ~~characterized in that~~ wherein the photoconductor (102, 202) is provided with an aperture (109, 209), and that the photoconductor (102, 202) is provided with electroconductive material at least around the edges of the aperture (109, 209).

3. (currently amended) ~~A photoconductor (102, 202)~~ The apparatus according to claim 1, ~~characterized in that in the photoconductor (202), there~~ wherein the electroconductive material is integrated with the photoconductor as a layer of electroconductive material [[210]] that covers the whole surface of the photoconductor [[202]].

4. (currently amended) ~~A photoconductor (102, 202)~~ The apparatus according to claim 3, ~~characterized in that in the photoconductor (202), there~~ wherein the electroconductive material is integrated with the photoconductor as a layer of electroconductive material [[210]] for conducting light in the photoconductor [[202]] and for shielding the light source [[208]] against electrostatic pulses.

5. (currently amended) ~~A photoconductor (102, 202)~~ The apparatus according to ~~any of the preceding claims, characterized in that~~ claim 1, wherein the electroconductive material (110, 210) is metal and ~~[[it]]~~ is connectable to the ground plane through the electroconductive material ~~[[(111)]]~~.

6. (currently amended) ~~A photoconductor (102, 202)~~ The apparatus according to ~~any of the preceding claims, characterized in that~~ claim 1, wherein the electroconductive material (110, 210) is realized on the surface of the photoconductor (102, 202) by ~~means of~~ an electroconductive film, or by inducing chemically or electrochemically.

7. (currently amended) An apparatus for shielding a component against electrostatic discharge, ~~said apparatus~~ comprising a light emitting diode (108, 208) and a photoconductor layer (102, 202) for conducting the light emitted by the light emitting diode (108, 208), ~~characterized in that~~ wherein the photoconductor layer (102, 202) includes electroconductive material (110, 210), and that the electroconductive material is connectable to ~~[[the]]~~ a ground plane ~~[[(111)]]~~ in order to conduct electrostatic discharges from the photoconductor layer (102, 202) to the ground plane.

8. (currently amended) ~~[[An]]~~ The apparatus according to claim 7, ~~characterized in that~~ wherein the photoconductor layer (102, 202) is provided with an aperture (109, 209), so that the light emitting diode (108, 208) is at least partly placed in the aperture (109, 209), inside the photoconductor layer (102, 202), and that the photoconductor layer (102, 202) is provided with electroconductive material at least around the edges of the aperture (109, 209).

9. (currently amended) ~~[[An]]~~ The apparatus according to claim 7, ~~characterized in that~~ wherein in the surface of the photoconductor layer (202), ~~in the surface thereof~~, there is integrated a layer of electroconductive material ~~[[(210)]]~~, said layer covering the whole surface of the photoconductor layer ~~[[(202)]]~~.

10. (currently amended) ~~[[An]]~~ The apparatus according to claim 9, ~~characterized in that wherein~~ in the surface of the photoconductor layer ~~[[(202)]]~~, there is integrated a layer of electroconductive material ~~[[(210)]]~~ for shielding the components against electrostatic pulses and for conducting the light emitted by the light emitting diode ~~[[(208)]]~~ in the photoconductor layer ~~[[(202)]]~~.

11. (currently amended) ~~[[An]]~~ The apparatus according to ~~any of the preceding claims, characterized in that~~ claim 7, wherein the light emitting diode ~~(108, 208)~~ is placed on a printed circuit board ~~(103, 203)~~, the photoconductor layer ~~(102, 202)~~ is placed on the component side of the circuit board ~~(103, 203)~~, and the electroconductive material ~~(110, 210)~~ is placed on that side of the photoconductor layer ~~(102, 202)~~ that faces away from the circuit board ~~(103, 203)~~ and the electroconductive material ~~(110, 210)~~ is connectable to the ground plane of the circuit board ~~(103, 203)~~.

12. (currently amended) ~~[[An]]~~ The apparatus according to ~~any of the preceding claims, characterized in that~~ claim 7, wherein the electroconductive material ~~(110, 210)~~ is metal, and ~~[[that]]~~ it is connected to the ground plane by electroconductive material ~~[[(111)]]~~.

13. (currently amended) ~~[[An]]~~ The apparatus according to ~~any of the preceding claims, characterized in that~~ claim 7, wherein the electroconductive material ~~(110, 210)~~ is realized on the surface of the photoconductor layer ~~(102, 202)~~ by ~~means of~~ an electroconductive film, or by inducing chemically or electrochemically.

14. (currently amended) ~~[[An]]~~ The apparatus according to ~~any of the preceding claims, characterized in that~~ claim 7, wherein on the circuit board ~~(103, 203)~~, there is a light emitting diode ~~(108, 208)~~ for illuminating the keypad ~~(101, 201)~~, and that the ~~device~~ apparatus comprises a photoconductor layer ~~(102, 202)~~ for conducting the light emitted by the light emitting diode ~~(108, 208)~~ to a key ~~(104, 204)~~.

15. (canceled)

16. (currently amended) [[A]] The method according to claim ~~15, characterized in that~~ 21, wherein the photoconductor layer (~~102, 202~~) is provided with an aperture (~~109, 209~~), so that the light emitting diode (~~108, 208~~) placed on the circuit board (~~103, 203~~) is arranged at least partly in the aperture (~~109, 209~~), inside the photoconductor layer (~~102, 202~~), and that in the photoconductor layer (~~102, 202~~), there is induced electroconductive material (~~110, 210~~) at least around the edges of the aperture (~~109, 209~~).

17. (currently amended) [[A]] The method according to claim ~~15, characterized in that~~ claim 21, wherein on the outermost surface of the photoconductor layer ~~[[202]]~~, facing away from the circuit board, there is integrated a layer of electroconductive material ~~[[210]]~~, which layer covers the whole surface of the photoconductor layer.

18. (currently amended) [[A]] The method according to claim 17, ~~characterized in that~~ wherein the electroconductive material ~~[[210]]~~ is induced for shielding ~~[[the]]~~ components of the circuit board ~~[[203]]~~ against electrostatic pulses and for conducting the light emitted by the light emitting diode ~~[[208]]~~ of the circuit board ~~[[203]]~~ in the photoconductor layer ~~[[202]]~~.

19. (currently amended) [[A]] The method according to ~~any of the preceding claims, characterized in that~~ claim 21, wherein the electroconductive material (~~110, 210~~) is metallized to the photoconductor layer (~~102, 202~~) and connected to the ground plane ~~[[111]]~~ of the circuit board by electroconductive material.

20. (currently amended) [[A]] The method according to ~~any of the preceding claims, characterized in that~~ claim 21, wherein the electroconductive material (~~110, 210~~) is realized in the photoconductor layer (~~102, 202~~) by ~~means of~~ an electroconductive film, or by inducing chemically or electrochemically.

21. (new) A method comprising:
- placing a light emitting diode on a printed circuit board,
 - arranging a photoconductor layer on a component side of the circuit board,
 - inducing an electroconductive material to the photoconductor layer,
 - connecting the electroconductive material to a ground plane of the circuit board in order to conduct electrostatic discharges from the photoconductor layer to the ground plane of the circuit board.
22. (new) An apparatus comprising:
- means for providing a photoconductor having a surface,
 - means for providing an electroconductive material induced on said surface of the means for providing a photoconductor, which material is connectable to a ground plane in order to conduct electrostatic discharges through the means for providing an electroconductive material to the ground plane.